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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YASUO OMORI	03/21/2014
HIROKI HIRAI	03/21/2014
MASAAKI TABATA	03/21/2014
TAKAMARU AMANO	03/21/2014
TAKASHI TSUCHIYA	03/21/2014

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14346128

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PATENT 35779 FRAME: 0577

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ATTORNEY DOCKET NUMBER: FPCT13-301US

NAME OF SUBMITTER: GERALD E. HESPOS

SIGNATURE: /Gerald E. Hespos/

DATE SIGNED: 06/03/2015

Total Attachments: 2

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> PATENT REEL: 035779 FRAME: 0578

Atty. Ref.: FPCT13-301US

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignees, 1) AUTONETWORKS TECHNOLOGIES. LTD., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-850 Japan, 2) Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-8503 Japan and 3) SUMITOMO ELECTRIC INDUSTRIES, LTD., a corporation organized under the laws of Japan, located at 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka, 541-0041 Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "GROUND CONNECTION FITTING AND GROUND CONNECTION DEVICE USING SAME", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignee Is Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries at its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefor to said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patent to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

And The Commissioner Of Patents Is Hereby Authorized And Requested to issue any and all Letters Patent of the United States for said invention, to said assignee.

March 21, 2014	Yasuo Omori
Date	Yasuo Omori
March 21,2014	Hinoki Hirai
Date	Hiroki Hirai
March 21, 2014	Masaaki Tabata
Date	Masaaki Tabata

PATENT REEL: 035779 FRAME: 0579 March 21.2014

Date

March 21.2019

Date

Takamaru Amano

Takamaru Amano

Takashi Tsuchiya

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